LC450029PKB

1/4 and 1/3-Duty General-Purpose LCD Driver

ON Semiconductor®

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Overview

The LC450029PKB is 1/4 duty and 1/3 duty general-purpose microcontroller-controlled LCD drivers that can be used in applications such as frequency display in products with electronic tuning. In addition to being capable to drive up to 208 segments directly. The internal oscillation circuit helps to reduce the number of external resistors and capacitors required. The chip shape is slim for COG (Chip-On-Glass) implementation. The operating temperature range is from –40°C to +105°C

Application

- Car or general consumer electronic LCD display equipment.

Features

- Selectable 1/4-duty or 1/3-duty drive by the serial control data
  When 1/4-duty: Capable of driving up to 208 segments
  When 1/3-duty: Capable of driving up to 159 segments
- 1/3-bias only
- Serial data input supports CCB* format communication with the system controller. (For 5 V operation only)
- The power-saving mode is selectable by the serial control data, and supports low power consumption.
- Adjustable the frame frequency of the common and segment output waveforms by the serial control data
- Selectable the internal oscillator operating or external clock operating mode by the serial control data
- High generality, since display data is displayed directly without the intervention of a decoder circuit.
- The $\overline{\text{INH}}$ pad allows all LCD segments to be forced to the off state.
- With a built-in oscillator circuit
  (External resistors and capacitors are unnecessary.)
- The stability of the LCD bias voltage is high by a built-in LCD bias generator with voltage-follower buffers.
- Shipping form: Chip with Au bumps in tray.
- Allowable operating voltage (V_{DD}, $V_{DD}I$) : +4.5 V to +6.0 V
- Allowable wide operating temperature ranges : –40°C to +105°C

* Computer Control Bus (CCB) is an ON Semiconductor's original bus format and the bus addresses are controlled by ON Semiconductor.

ORDERING INFORMATION

See detailed ordering and shipping information on page 25 of this data sheet.

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LC450029PKB/D

Specifications

Absolute Maximum Ratings at Ta = 25°C, V_{SS} = 0 V

Parameter	Symbol	Conditions	Ratings	Unit
Maximum supply voltage	V_{DD} max, V_{DD}I max	V_{DD}=V_{DD}I	−0.3 to +6.5	V
Input voltage	V_{IN}1	CE, CL, DI, $\overline{INH}$	−0.3 to +6.5	V
	V_{IN}2	OSCI	−0.3 to V_{DD}I+0.3	
Output voltage	V_{OUT}	S1 to S53, COM1 to COM4	−0.3 to V_{DD}+0.3	V
Output current	I_{OUT}1	S1 to S53	300	μA
	I_{OUT}2	COM1 to COM4	3	mA
Operating temperature	Topr		−40 to +105	°C
Storage temperature	Tstg		−55 to +125	°C

(Note) Power supply pads (V_{DD}, V_{DD}I) should connect all pads to the same power supply.
(See sample applications circuits)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Allowable Operating Ranges at Ta = −40 to +105°C, V_{SS} = 0 V

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
Supply voltage	V_{DD}, V_{DD}I	V_{DD}=V_{DD}I	4.5		6.0	V
Input high-level voltage	V_{IH}1	CE, CL, DI, $\overline{INH}$	0.8V_{DD}		6.0	V
	V_{IH}2	OSCI: External clock operating mode	0.8V_{DD}		V_{DD}I	
Input low-level voltage	V_{IL}1	CE, CL, DI, $\overline{INH}$	0		0.2V_{DD}I	V
	V_{IL}2	OSCI: External clock operating mode	0		0.2V_{DD}I	
External clock operating frequency	f_{CK}	OSCI: External clock operating mode [Figure 4]	10	300	600	kHz
External clock duty cycle	D_{CK}	OSCI: External clock operating mode [Figure 4]	30	50	70	%
Data setup time	tds	CL, DI [Figure 2] [Figure 3]	160			ns
Data hold time	tdh	CL, DI [Figure 2] [Figure 3]	160			ns
CE wait time	tcp	CE, CL [Figure 2] [Figure 3]	160			ns
CE setup time	tcs	CE, CL [Figure 2] [Figure 3]	160			ns
CE hold time	tch	CE, CL [Figure 2] [Figure 3]	160			ns
High-level clock pulse width	tϕH	CL [Figure 2] [Figure 3]	160			ns
Low-level clock pulse width	tϕL	CL [Figure 2] [Figure 3]	160			ns
Rise time	tr	CE, CL, DI [Figure 2] [Figure 3]		160		ns
Fall time	tf	CE, CL, DI [Figure 2] [Figure 3]		160		ns
$\overline{INH}$ switching time	tc	$\overline{INH}$, CE [Figure 5] [Figure 6]	10			μs

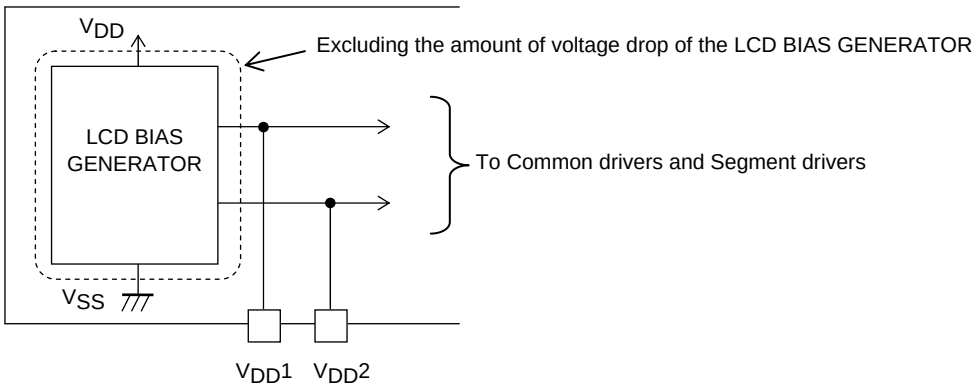
(Note) Power supply pads (V_{DD}, V_{DD}I) should connect all pads to the same power supply.
(See sample applications circuits)

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

Electrical Characteristics for the Allowable Operating Ranges

Parameter	Symbol	Pin	Conditions	Ratings			Unit
				min	typ	max	
Hysteresis	V_H1	CE, CL, DI, $\overline{INH}$			$0.1V_{DD}I$		V
	V_H2	OSCI	External clock operating mode		$0.1V_{DD}I$		
Input high-level current	$I_{IH}1$	CE, CL, DI, $\overline{INH}$	V_I = 6.0 V			5.0	μA
	$I_{IH}2$	OSCI	$V_I = V_{DD}I$, External clock operating mode			5.0	
Input low-level current	$I_{IL}1$	CE, CL, DI, $\overline{INH}$	V_I = 0 V	−5.0			μA
	$I_{IL}2$	OSCI	V_I = 0 V, External clock operating mode	−5.0			
Output high-level voltage	$V_{OH}1$	S1 to S53	I_O = −20 μA	V_{DD} −0.9			V
	$V_{OH}2$	COM1 to COM4	I_O = −100 μA	V_{DD} −0.9			
Output low-level voltage	$V_{OL}1$	S1 to S53	I_O = 20 μA			0.9	V
	$V_{OL}2$	COM1 to COM4	I_O = 100 μA			0.9	
Output middle-level voltage *1	$V_{MID}1$	S1 to S53	I_O = ±20 μA	$2/3V_{DD}$ −0.9		$2/3V_{DD}$ +0.9	V
	$V_{MID}2$	S1 to S53	I_O = ±20 μA	$1/3V_{DD}$ −0.9		$1/3V_{DD}$ +0.9	
	$V_{MID}3$	COM1 to COM4	I_O = ±100 μA	$2/3V_{DD}$ −0.9		$2/3V_{DD}$ +0.9	
	$V_{MID}4$	COM1 to COM4	I_O = ±100 μA	$1/3V_{DD}$ −0.9		$1/3V_{DD}$ +0.9	
Oscillator frequency	fosc	Internal oscillator circuit	Internal oscillator operating mode	210	300	390	kHz
Current drain (Total value of V_{DD} and $V_{DD}I$)	$I_{DD}1$	V_{DD}, $V_{DD}I$	<Power-saving mode> $V_{DD} = V_{DD}I$ = 6.0 V		40	100	μA
	$I_{DD}2$	V_{DD}, $V_{DD}I$	<Internal oscillator operating mode> $V_{DD} = V_{DD}I$ = 6.0 V Driver outputs are open.		200	400	
	$I_{DD}3$	V_{DD}, $V_{DD}I$	<External clock operating mode> $V_{DD} = V_{DD}I$ = 6.0 V f_{CK} = 300 kHz Driver outputs are open.		170	340	

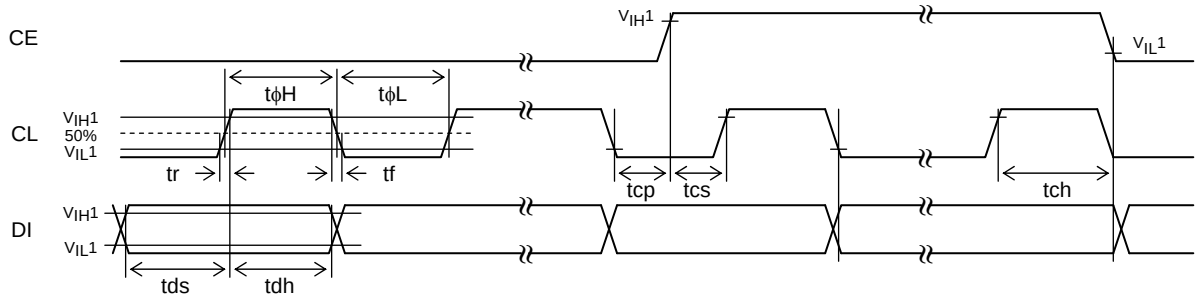
*1: Excluding the amount of voltage drop of the LCD BIAS GENERATOR which generates $V_{DD}1$ and $V_{DD}2$. (See Figure 1.)



[Figure 1]

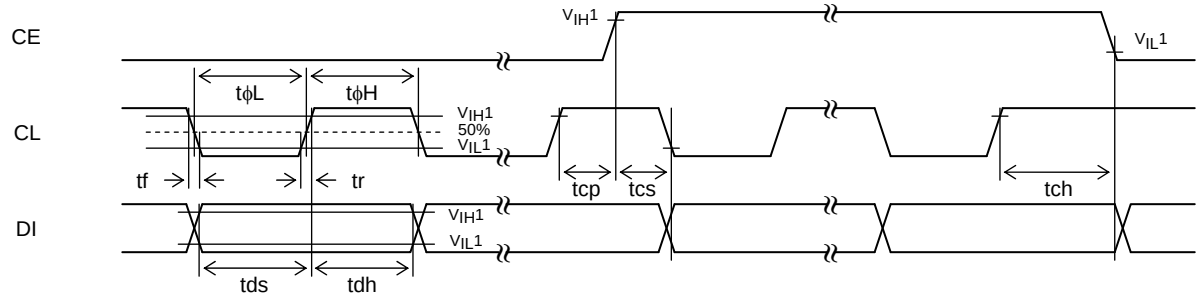
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

(1) When CL is stopped at the low level



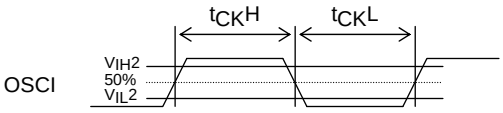
[Figure 2]

(2) When CL is stopped at the high level



[Figure 3]

(3) OSCI pad clock timing in external clock operating mode

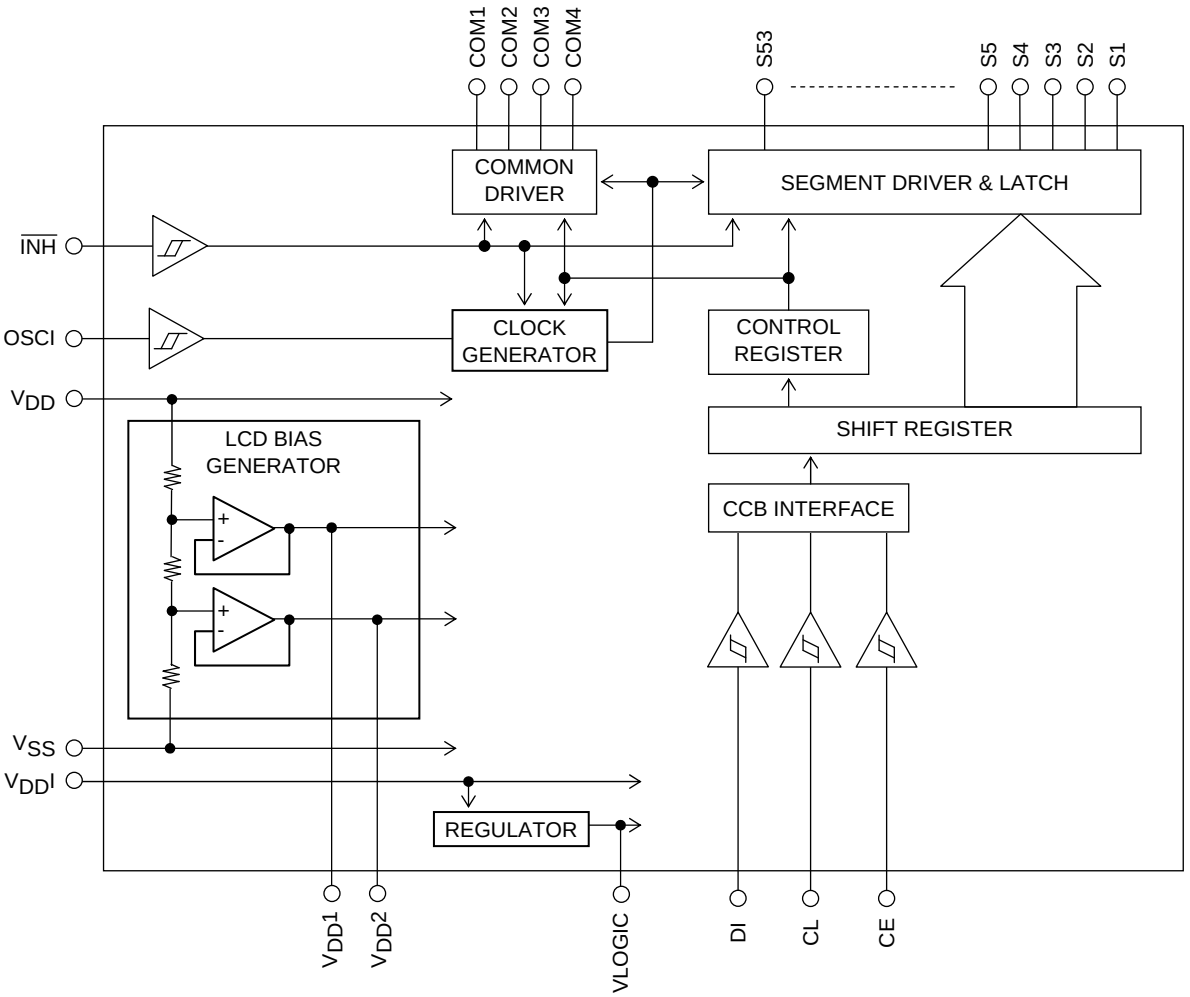


$$f_{CK} = \frac{1}{t_{CK}H + t_{CK}L} \quad [kHz]$$

$$D_{CK} = \frac{t_{CK}H}{t_{CK}H + t_{CK}L} \times 100[\%]$$

[Figure 4]

Block Diagram



Pad Functions

Symbol	Pad No.	Function	Active	I/O	Handling when unused
COM1 to COM4	2 to 5	Common driver outputs. The frame frequency is fo[Hz]. COM4 pad outputs the V_{SS} level in 1/3-duty.	-	O	OPEN
S1 to S53	6 to 58	Segment outputs for displaying the display data transferred by serial data input. S51 pad outputs the V_{SS} level in 1/4-duty. S52 pad and S53 pad output the V_{SS} level at the control data DN="0". S53 pad outputs the V_{SS} level at external clock operating mode.	-	O	OPEN
$\overline{INH}$	61	Display off control input • $\overline{INH}$ = low (V_{SS}) ...Display forced off (V_{SS} level Output) S1 to S53 = low (V_{SS}) COM1 to COM4 = low (V_{SS}) The internal oscillator stops. Stops inputting external clock. Serial data transfer can be used. • $\overline{INH}$ = high (V_{DD})...Display on Enables the internal oscillator circuit. (Internal oscillator operating mode) Enables external clock input. (External clock operating mode) While display on, LCD outputs force off (V_{SS} level output) by the control data BU="1". While display on, LCD outputs off (off waveforms output) by the control data SC="1".	L	I	GND (V_{SS})
CE DI CL	62 63 64	Serial data transfer inputs. Must be connected to the controller. CE: Chip enable DI: Transfer data CL: Synchronization clock	H - ↑	I I I	GND (V_{SS})
VLOGIC	65	Used to monitor pad for the power supply voltage of the logic circuit.	-	O	OPEN
V_{DD}I	66 to 71	Power supply pad. A power voltage of 4.5 to 6.0V must be applied to these pads.	-	-	-
OSCI	72	This pad can also be used as the external clock input pad when the external clock operating mode is selected by control data. This pad must be connected to GND at internal oscillator operating mode.	-	I	GND (V_{SS})
V_{SS}	73 to 90	Ground pad. Must be connected to ground.	-	-	-
V_{DD}2	91	Used to monitor pad for the LCD drive bias voltage (1/3 V_{DD}).	-	O	OPEN
V_{DD}1	92	Used to monitor pad for the LCD drive bias voltage (2/3 V_{DD}).	-	O	OPEN
V_{DD}	93 to 105	Power supply pad. A power voltage of 4.5 to 6.0V must be applied to these pads.	-	-	-
DUMMY	1, 59, 60, 106	Dummy pad. Must not be used.	-	OPEN	OPEN

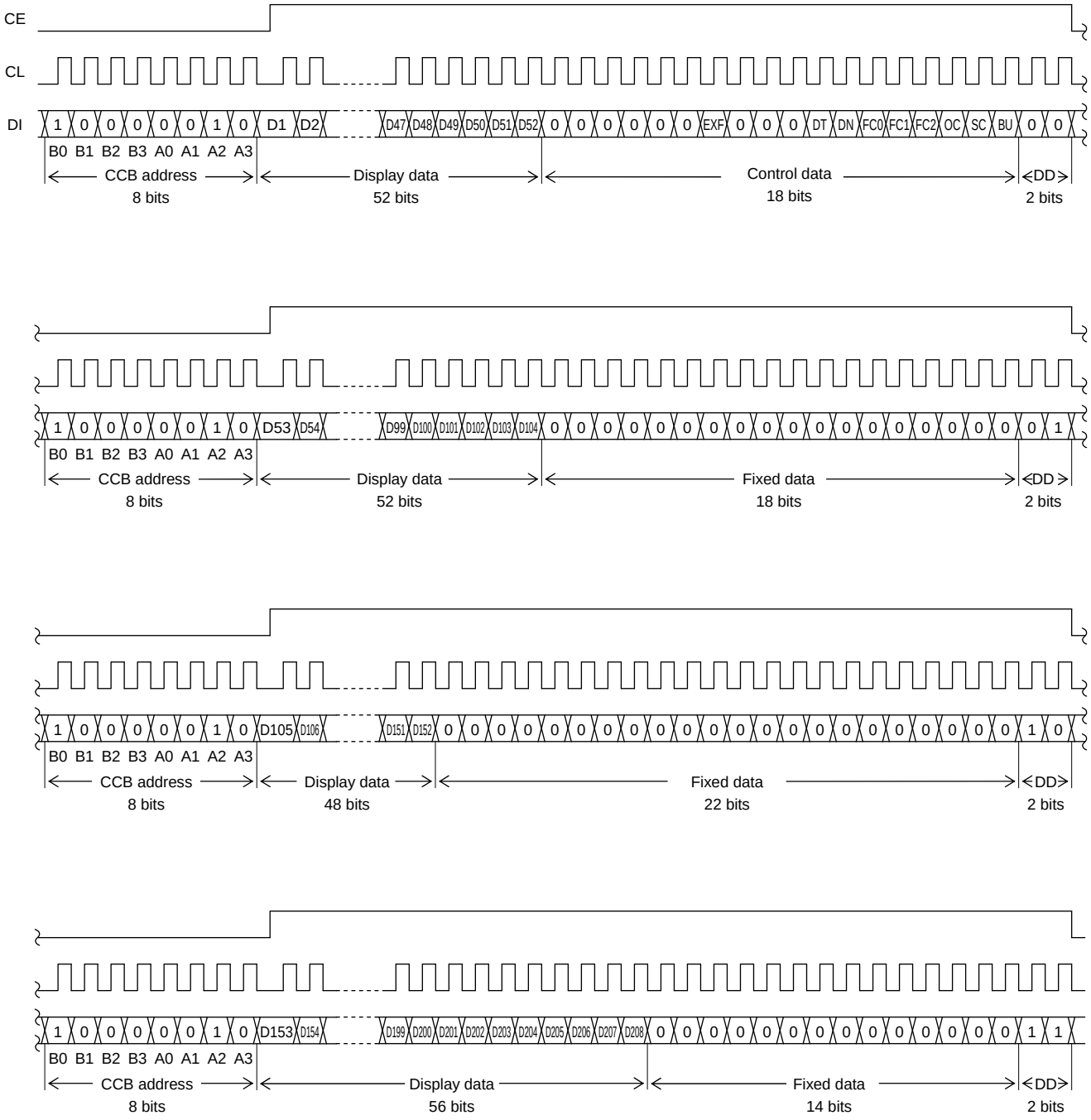
(Note)

- Power supply pads (V_{DD}, V_{DD}I) should connect all pads to the same power supply. (See sample applications circuits)
- GND pad (V_{SS}) should connect all pads to the GND.
- When logic input pads ($\overline{INH}$, CE, DI, CL, OSCI) are not used, must be fixed to GND (V_{SS}).
- Must not use monitor pads (VLOGIC, V_{DD}1, V_{DD}2) in an external circuit.
- Must not connect dummy pad (DUMMY) mutually. Moreover, never use it in an external circuit.

Serial Data Input

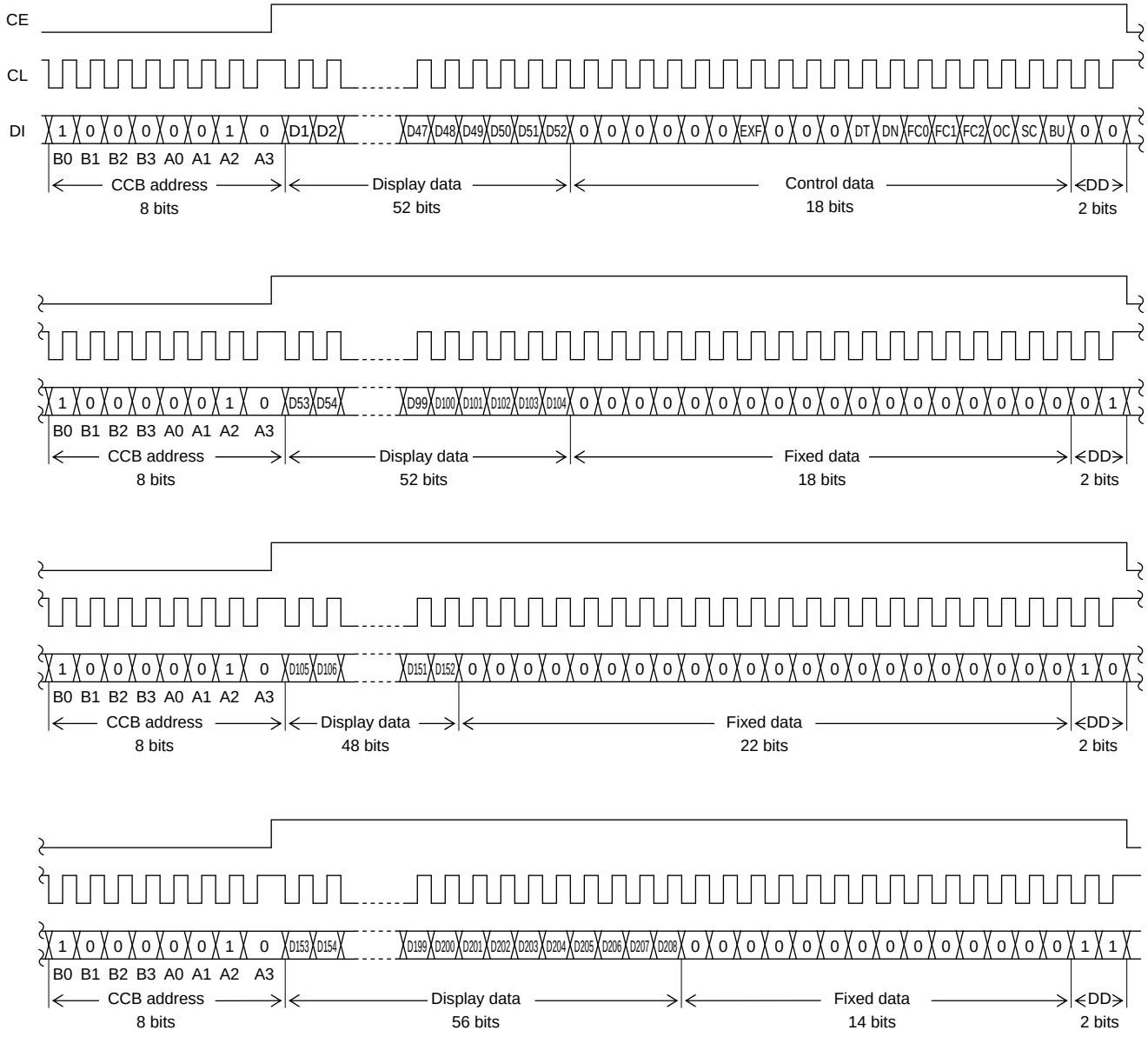
1. 1/4 duty

(1) When CL is stopped at the low level



Note: DD is the direction data.

(2) When CL is stopped at the high level

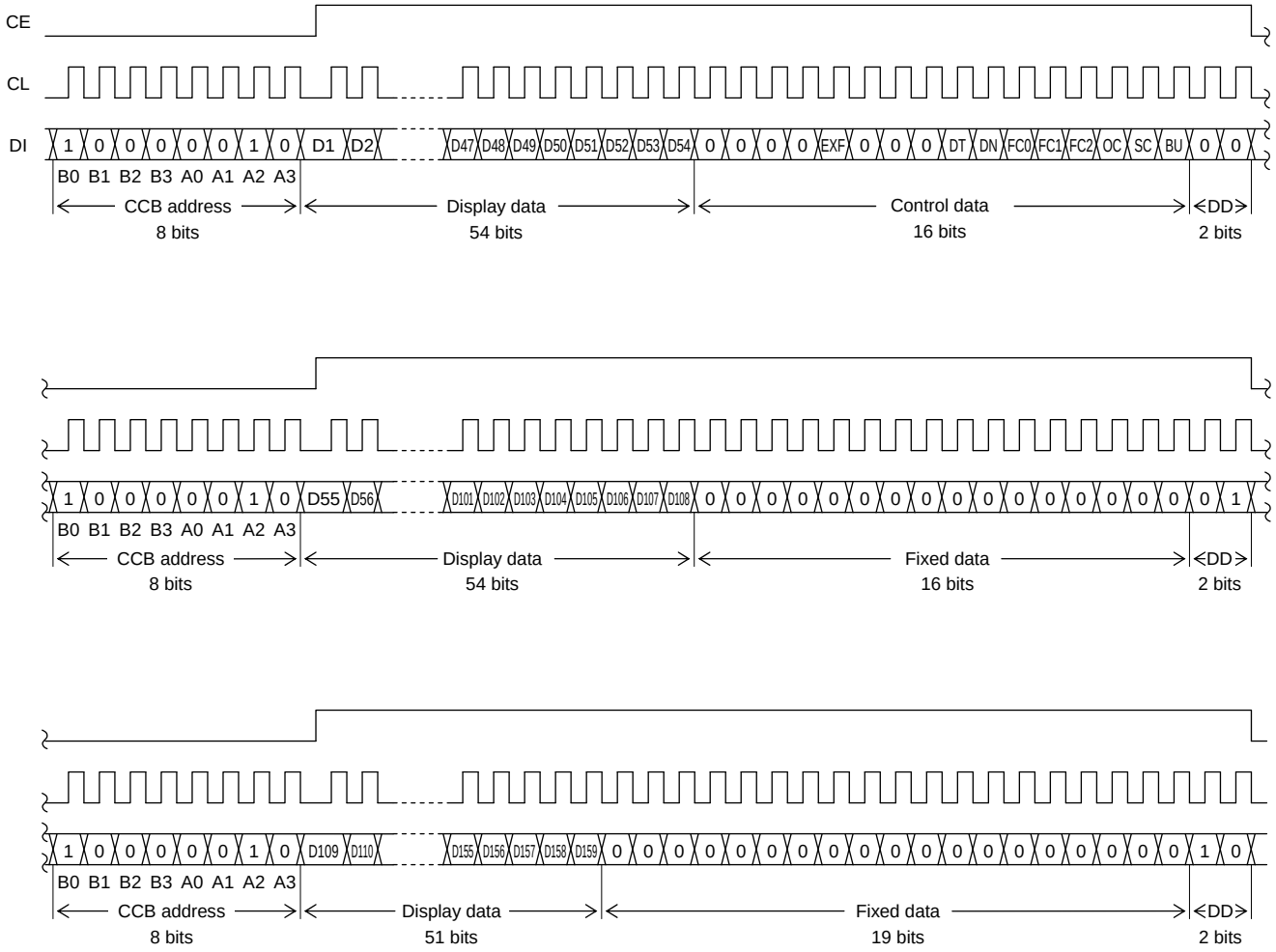


Note: DD is the direction data.

- CCB address ..... “41H”
- D1 to D208 ..... Display data
- EXF ..... Ratio of dividing frequency in external clock operating mode setting control data
- DT ..... 1/4-duty drive or 1/3-duty drive switching control data
- DN ..... The number of the maximum display segments setting control data
- FC0 to FC2 ..... Common/segment output waveform frame frequency control data
- OC ..... Internal oscillator operating mode/external clock operating mode switching control data
- SC ..... Segment on/off (off waveform output) control data
- BU ..... Normal mode/power-saving mode control data

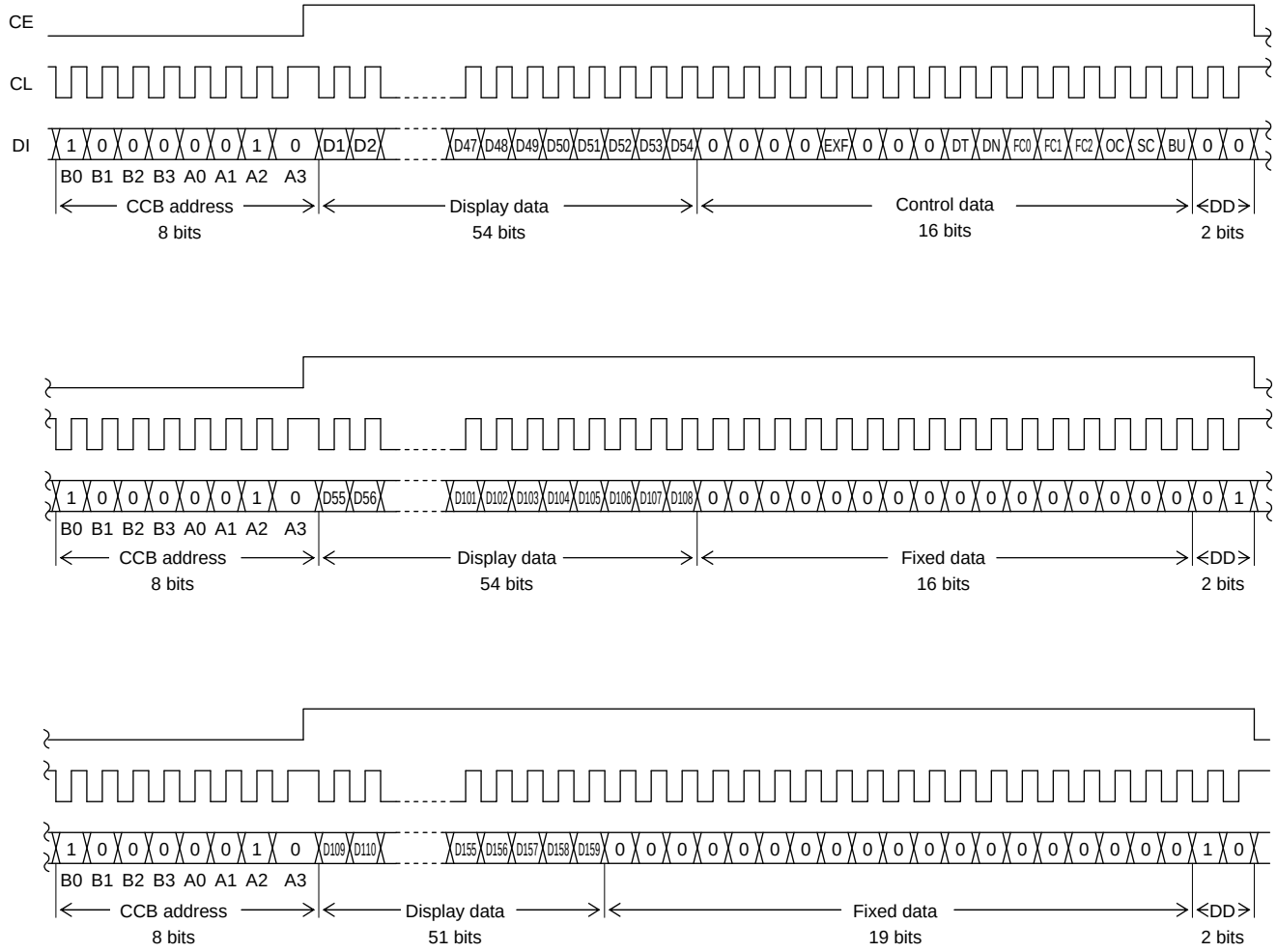
2. 1/3 duty

(1) When CL is stopped at the low level



Note: DD is the direction data.

(2) When CL is stopped at the high level



Note: DD is the direction data.

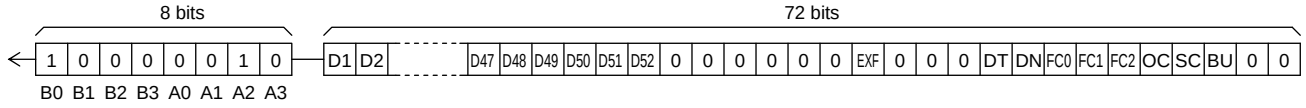
- CCB address ..... “41H”
- D1 to D208 ..... Display data
- EXF ..... Ratio of dividing frequency in external clock operating mode setting control data
- DT ..... 1/4-duty drive or 1/3-duty drive switching control data
- DN ..... The number of the maximum display segments setting control data
- FC0 to FC2 ..... Common/segment output waveform frame frequency control data
- OC ..... Internal oscillator operating mode/external clock operating mode switching control data
- SC ..... Segment on/off (off waveform output) control data
- BU ..... Normal mode/power-saving mode control data

Serial Data Transfer Example

1. 1/4 duty

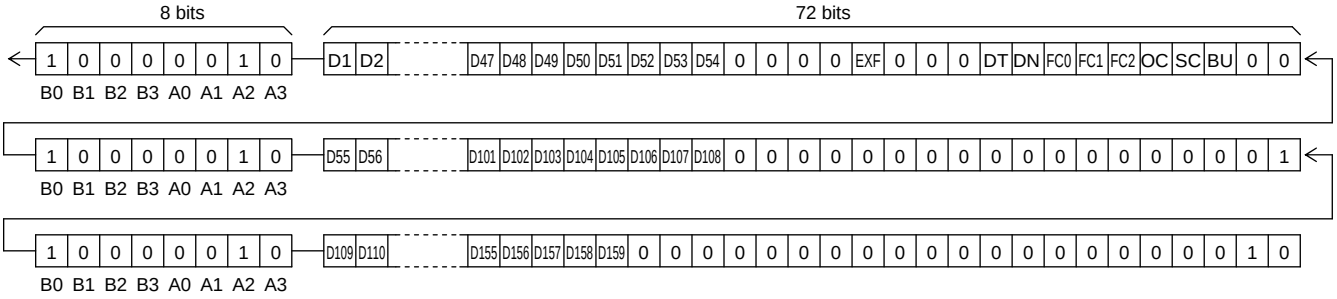
• When 153 or more segments are used
All 320 bits (include CCB address) of serial data must be sent.

• When fewer than 153 segments are used
One of 80, 160 and 240 bits of serial data must be sent, depending on the number of segments to be used.
However, the serial data shown below (the D1 to D52 display data, the control data and DD="00") must always be sent.

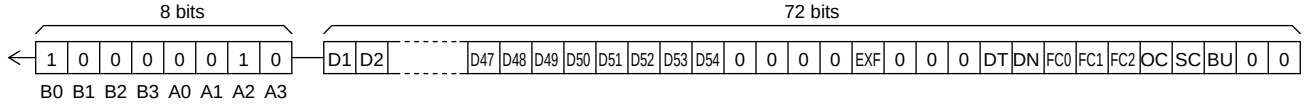


2. 1/3 duty

• When 109 or more segments are used
All 240 bits (include CCB address) of serial data must be sent.



• When fewer than 109 segments are used
Either 80 or 160 bits of serial data must be sent, depending on the number of segments to be used.
However, the serial data shown below (the D1 to D54 display data, the control data and DD="00") must always be sent.



Control Data Functions

(1) EXF … Ratio of dividing frequency in external clock operating mode setting control data

This control data sets the ratio of dividing frequency of the external clock which input into the OSCI pad, when the external clock operating mode (OC="1") is set. However, this data is effective only when external clock operating mode (OC= "1") is set. The frame frequency is adjustable by setting EXF, FC0 to FC2 and OC.

EXF	Ratio of dividing frequency in external clock operating mode
0	f_{CK} / 8
1	f_{CK}

(2) DT …1/4-duty drive or 1/3-duty drive switching control data

This control data bit selects either 1/4-duty drive or 1/3-duty drive.

DT	Drive scheme	S51 pad's state
0	1/4-duty drive	Low (V_{SS}) level output
1	1/3-duty drive	S51 (segment output)

(3) DN …The number of the maximum display segments setting control data

This control data bit sets the number of the maximum display segments.

DN	The number of the maximum display segments		Pad's state	
	1/4 duty	1/3 duty	S52	S53
0	Up to 200 segments	Up to 153 segments	"L" (V_{SS})	"L" (V_{SS})
1	Up to 208 segments	Up to 159 segments	S52 (segment output)	S53 (segment output)

(Note) S53 pad outputs V_{SS} level in external clock operating mode.

(4) FC0 to FC2 …Common/segment output waveform frame frequency control data

These control data bits set the frame frequency of the common and segment output waveforms. The frame frequency is adjustable by setting EXF, FC0 to FC2 and OC.

Control data			Frame frequency fo[Hz]		
FC0	FC1	FC2	Internal oscillator operating mode (The control data OC="0", fosc=300[kHz]typ)	External clock operating mode (The control data OC="1", EXF="0") Case is f_{CK}=300[kHz].	External clock operating mode (The control data OC="1", EXF="1") Case is f_{CK}=38[kHz].
0	0	0	fosc/6144 =48.8[Hz]typ	f_{CK}/6144 =48.8[Hz]	f_{CK}/768 =49.5[Hz]
0	0	1	fosc/4608 =65.1[Hz]typ	f_{CK}/4608 =65.1[Hz]	f_{CK}/576 =66.0[Hz]
0	1	0	fosc/3072 =97.7[Hz]typ	f_{CK}/3072 =97.7[Hz]	f_{CK}/384 =99.0[Hz]
0	1	1	fosc/2304 =130.2[Hz]typ	f_{CK}/2304 =130.2[Hz]	f_{CK}/288 =131.9[Hz]
1	0	0	fosc/1536 =195.3[Hz]typ	f_{CK}/1536 =195.3[Hz]	f_{CK}/192 =197.9[Hz]
1	0	1	fosc/1152 =260.4[Hz]typ	f_{CK}/1152 =260.4[Hz]	f_{CK}/144 =263.9[Hz]
1	1	0	fosc/768 =390.6[Hz]typ	f_{CK}/768 =390.6[Hz]	f_{CK}/96 =395.8[Hz]
1	1	1	fosc/3072 =97.7[Hz]typ	f_{CK}/3072 =97.7[Hz]	f_{CK}/384 =99.0[Hz]

(5) OC …Internal oscillator operating mode/external clock operating mode switching control data

This control data bit selects either the internal oscillator operating mode or external clock operating mode.

OC	Fundamental clock operating mode	S53 pad's state
0	Internal oscillator operating mode	S53 (segment output)
1	External clock operating mode	Low (V_{SS}) level output

(6) SC … Segment on/off (off waveform output) control data

This control data bit controls the on/off (off waveform output) state of all the segments.

SC	Display state
0	On
1	Off of all the segments (off waveform output)

(7) BU … Normal mode/power-saving mode control data

This control data bit selects either normal mode or power-saving mode.

BU	Mode
0	Normal mode
1	Power-saving mode (All of the common and segment output pads output the V_{SS} level. In this mode, the internal oscillator circuit stops oscillation if the IC is in the internal oscillator operating mode (OC=0), and the IC stops receiving external clock signals if the IC is in the external clock operating mode (OC=1).)

Display Data and Output Pad Correspondence (1/4 Duty)

Output pad	COM1	COM2	COM3	COM4
S1	D1	D2	D3	D4
S2	D5	D6	D7	D8
S3	D9	D10	D11	D12
S4	D13	D14	D15	D16
S5	D17	D18	D19	D20
S6	D21	D22	D23	D24
S7	D25	D26	D27	D28
S8	D29	D30	D31	D32
S9	D33	D34	D35	D36
S10	D37	D38	D39	D40
S11	D41	D42	D43	D44
S12	D45	D46	D47	D48
S13	D49	D50	D51	D52
S14	D53	D54	D55	D56
S15	D57	D58	D59	D60
S16	D61	D62	D63	D64
S17	D65	D66	D67	D68
S18	D69	D70	D71	D72
S19	D73	D74	D75	D76
S20	D77	D78	D79	D80
S21	D81	D82	D83	D84
S22	D85	D86	D87	D88
S23	D89	D90	D91	D92
S24	D93	D94	D95	D96
S25	D97	D98	D99	D100
S26	D101	D102	D103	D104
S27	D105	D106	D107	D108

Output pad	COM1	COM2	COM3	COM4
S28	D109	D110	D111	D112
S29	D113	D114	D115	D116
S30	D117	D118	D119	D120
S31	D121	D122	D123	D124
S32	D125	D126	D127	D128
S33	D129	D130	D131	D132
S34	D133	D134	D135	D136
S35	D137	D138	D139	D140
S36	D141	D142	D143	D144
S37	D145	D146	D147	D148
S38	D149	D150	D151	D152
S39	D153	D154	D155	D156
S40	D157	D158	D159	D160
S41	D161	D162	D163	D164
S42	D165	D166	D167	D168
S43	D169	D170	D171	D172
S44	D173	D174	D175	D176
S45	D177	D178	D179	D180
S46	D181	D182	D183	D184
S47	D185	D186	D187	D188
S48	D189	D190	D191	D192
S49	D193	D194	D195	D196
S50	D197	D198	D199	D200
S51	-	-	-	-
S52	D201	D202	D203	D204
S53	D205	D206	D207	D208

(Note) In external clock operating mode, S53 pad outputs V_{SS} level. When DN is “0”, S52 pad and S53 pad output V_{SS} level. When duty is 1/4, S51 pad outputs V_{SS} level.

For example, the table below lists the output states for the S21 output pad.

Display data				Output pad (S21) state
D81	D82	D83	D84	
0	0	0	0	The LCD segments corresponding to COM1, COM2, COM3, and COM4 are off.
0	0	0	1	The LCD segment corresponding to COM4 is on.
0	0	1	0	The LCD segment corresponding to COM3 is on.
0	0	1	1	The LCD segments corresponding to COM3 and COM4 are on.
0	1	0	0	The LCD segment corresponding to COM2 is on.
0	1	0	1	The LCD segments corresponding to COM2 and COM4 are on.
0	1	1	0	The LCD segments corresponding to COM2 and COM3 are on.
0	1	1	1	The LCD segments corresponding to COM2, COM3, and COM4 are on.
1	0	0	0	The LCD segment corresponding to COM1 is on.
1	0	0	1	The LCD segments corresponding to COM1 and COM4 are on.
1	0	1	0	The LCD segments corresponding to COM1 and COM3 are on.
1	0	1	1	The LCD segments corresponding to COM1, COM3, and COM4 are on.
1	1	0	0	The LCD segments corresponding to COM1 and COM2 are on.
1	1	0	1	The LCD segments corresponding to COM1, COM2, and COM4 are on.
1	1	1	0	The LCD segments corresponding to COM1, COM2, and COM3 are on.
1	1	1	1	The LCD segments corresponding to COM1, COM2, COM3, and COM4 are on.

Display Data and Output Pad Correspondence (1/3 Duty)

Output pad	COM1	COM2	COM3
S1	D1	D2	D3
S2	D4	D5	D6
S3	D7	D8	D9
S4	D10	D11	D12
S5	D13	D14	D15
S6	D16	D17	D18
S7	D19	D20	D21
S8	D22	D23	D24
S9	D25	D26	D27
S10	D28	D29	D30
S11	D31	D32	D33
S12	D34	D35	D36
S13	D37	D38	D39
S14	D40	D41	D42
S15	D43	D44	D45
S16	D46	D47	D48
S17	D49	D50	D51
S18	D52	D53	D54
S19	D55	D56	D57
S20	D58	D59	D60
S21	D61	D62	D63
S22	D64	D65	D66
S23	D67	D68	D69
S24	D70	D71	D72
S25	D73	D74	D75
S26	D76	D77	D78
S27	D79	D80	D81

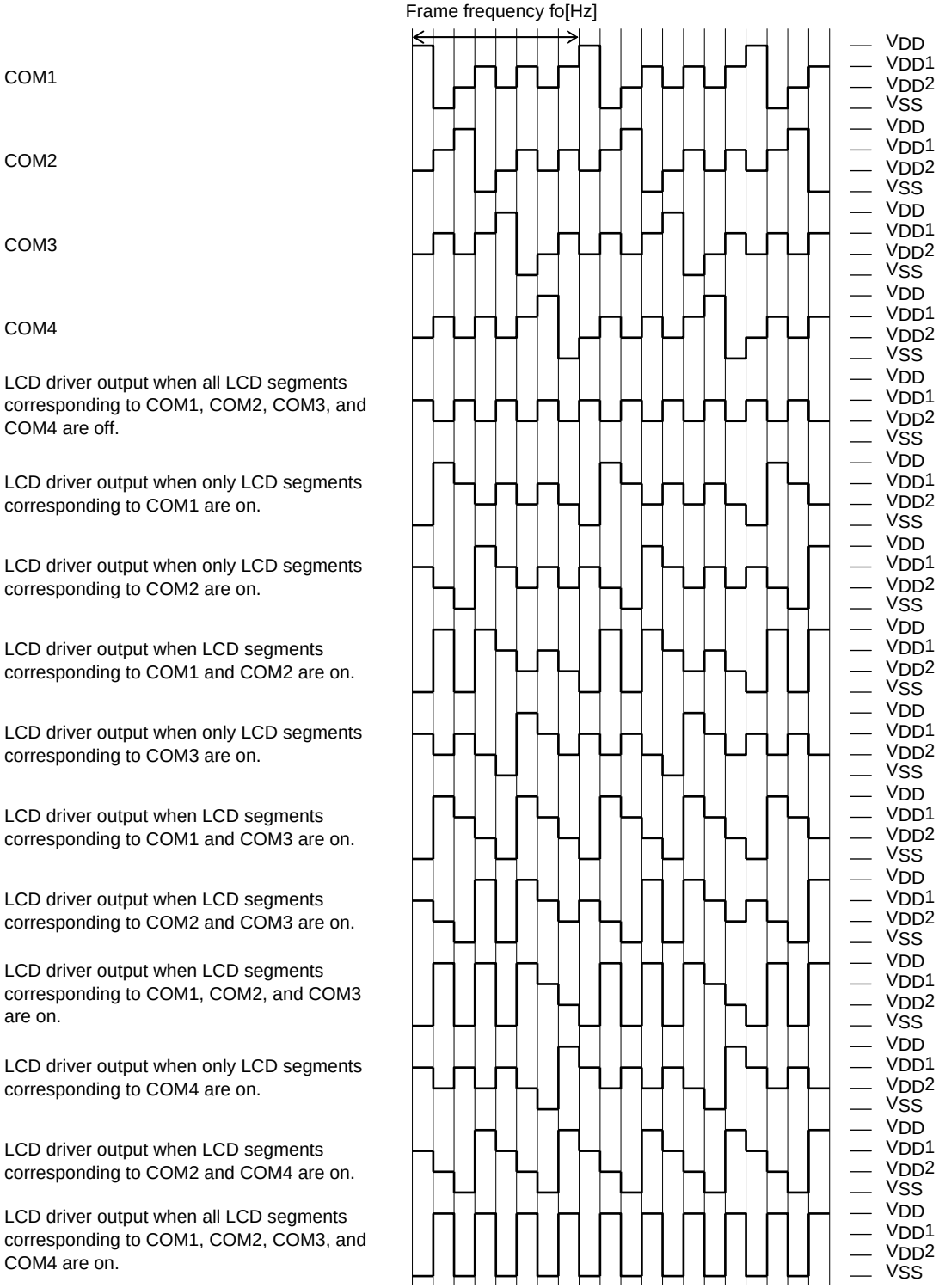
Output pad	COM1	COM2	COM3
S28	D82	D83	D84
S29	D85	D86	D87
S30	D88	D89	D90
S31	D91	D92	D93
S32	D94	D95	D96
S33	D97	D98	D99
S34	D100	D101	D102
S35	D103	D104	D105
S36	D106	D107	D108
S37	D109	D110	D111
S38	D112	D113	D114
S39	D115	D116	D117
S40	D118	D119	D120
S41	D121	D122	D123
S42	D124	D125	D126
S43	D127	D128	D129
S44	D130	D131	D132
S45	D133	D134	D135
S46	D136	D137	D138
S47	D139	D140	D141
S48	D142	D143	D144
S49	D145	D146	D147
S50	D148	D149	D150
S51	D151	D152	D153
S52	D154	D155	D156
S53	D157	D158	D159

(Note) In external clock operating mode, S53 pad outputs V_{SS} level. When DN is “0”, S52 pad and S53 pad output V_{SS} level.

For example, the table below lists the output states for the S21 output pad.

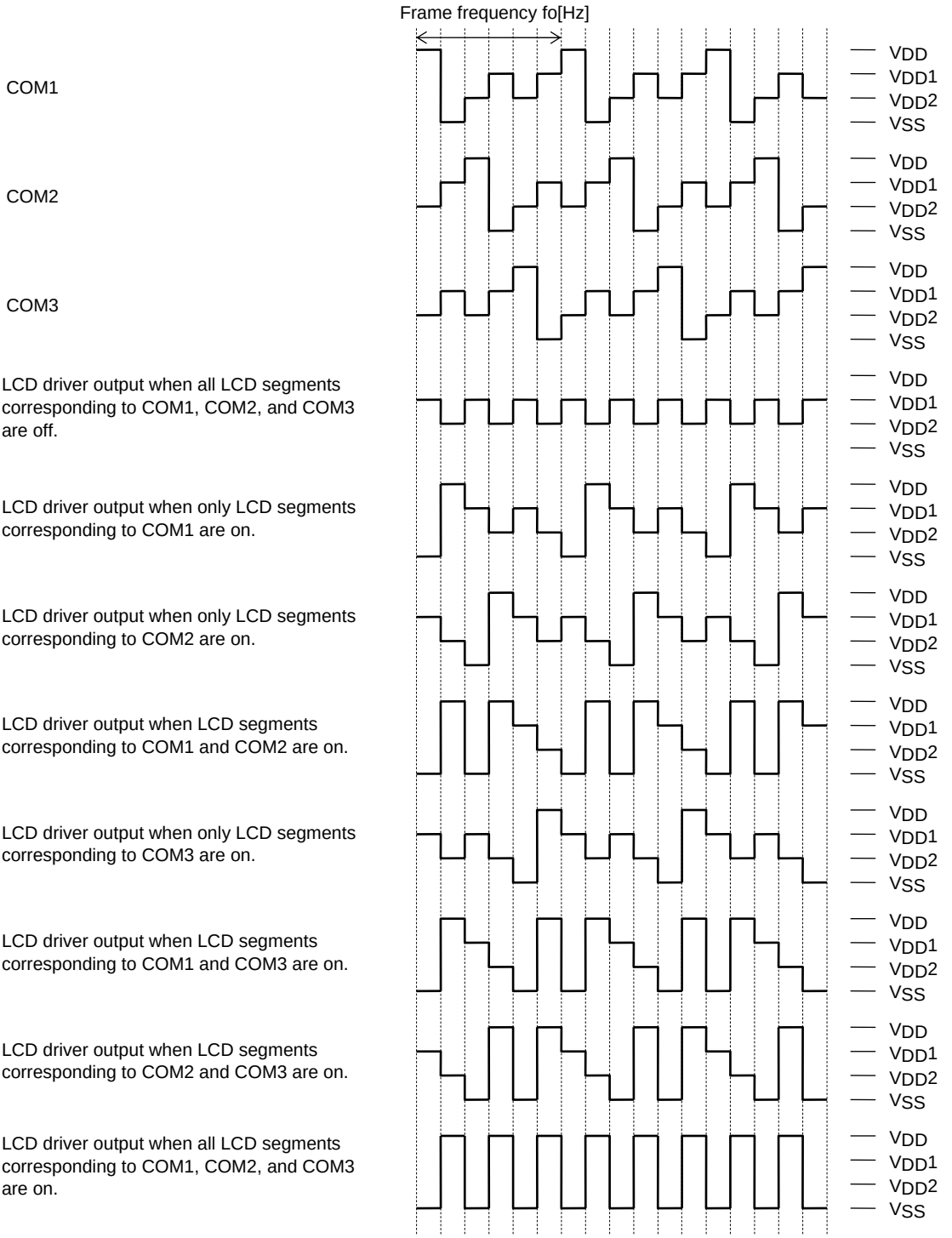
Display data			Output pad (S21) state
D61	D62	D63	
0	0	0	The LCD segments corresponding to COM1, COM2, and COM3 are off.
0	0	1	The LCD segment corresponding to COM3 is on.
0	1	0	The LCD segment corresponding to COM2 is on.
0	1	1	The LCD segments corresponding to COM2 and COM3 are on.
1	0	0	The LCD segment corresponding to COM1 is on.
1	0	1	The LCD segments corresponding to COM1 and COM3 are on.
1	1	0	The LCD segments corresponding to COM1 and COM2 are on.
1	1	1	The LCD segments corresponding to COM1, COM2, and COM3 are on.

Output Waveforms (1/4-Duty 1/3-Bias Drive Scheme)



(Note) The frame frequency fo[Hz] is adjustable by setting control data (EXF, FC0 to FC2 and OC).
(See “Control Data Functions” for details)

Output Waveforms (1/3-Duty 1/3-Bias Drive Scheme)

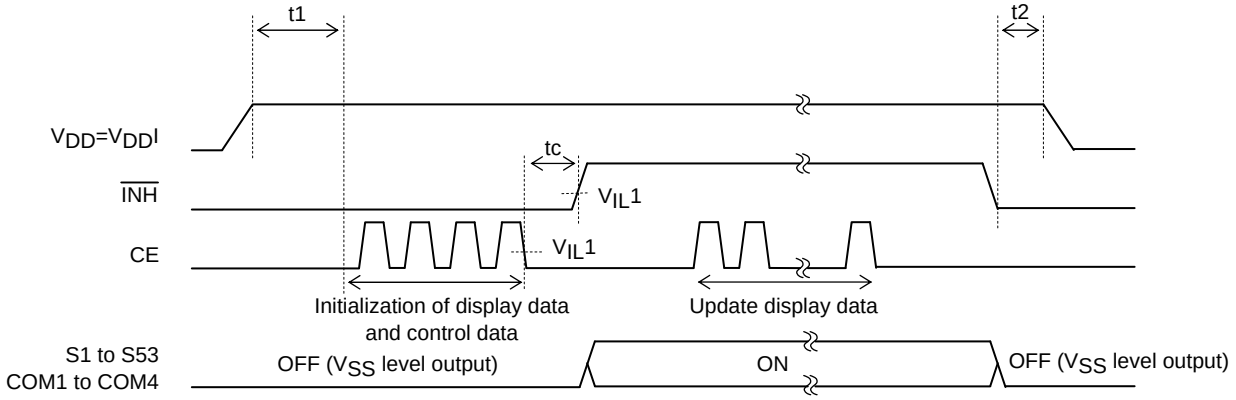


(Note) The frame frequency fo[Hz] is adjustable by setting control data (EXF, FC0 to FC2 and OC).
(See “Control Data Functions” for details)

Display Control and the $\overline{INH}$ Pad

Since the LSI internal data (1/4 duty : the display data D1 to D208 and the control data, 1/3 duty : the display data D1 to D159 and the control data) is undefined when power is first applied. Applications should set the $\overline{INH}$ pad low at the same time as power is applied to turn off the display (This sets the S1 to S53 and COM1 to COM4 pads the V_{SS} level.) and during this period send serial data from the controller. The controller should then set the $\overline{INH}$ pad high after the data transfer has completed. This procedure prevents meaningless display at power on. V_{DD} and $V_{DD}I$ are connected with the same power supply. The timing of turn on and turn off for V_{DD} and $V_{DD}I$ should be same time.
(See from Figure 5 to Figure 8)

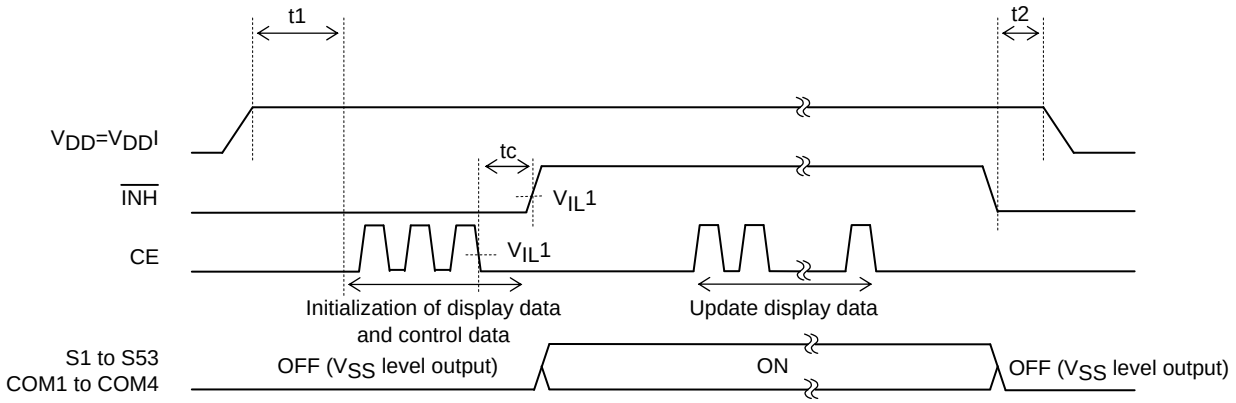
• 1/4 duty



(Note) The wait time (t1) which power supply turn on should be 1ms or more.
The discharge time (t2) of LCD panel's electric charge should be decided the optimum value according to the characteristic of the LCD panel.
The switching time (tc) of $\overline{INH}$ should be 10μs or more.

[Figure 5]

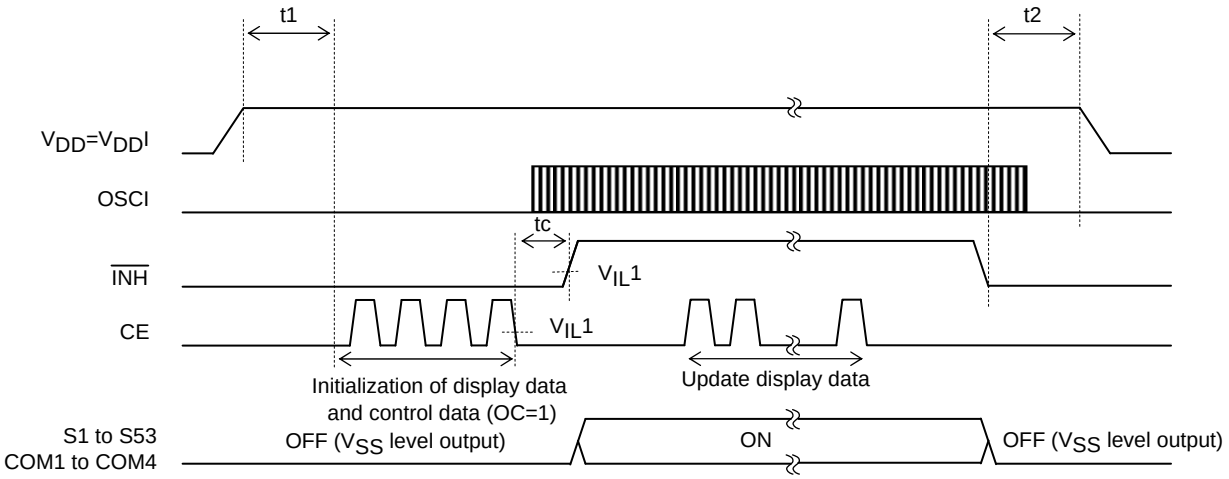
• 1/3 duty



(Note) The wait time (t1) which power supply turn on should be 1ms or more.
The discharge time (t2) of LCD panel's electric charge should be decided the optimum value according to the characteristic of the LCD panel.
The switching time (tc) of $\overline{INH}$ should be 10μs or more.

[Figure 6]

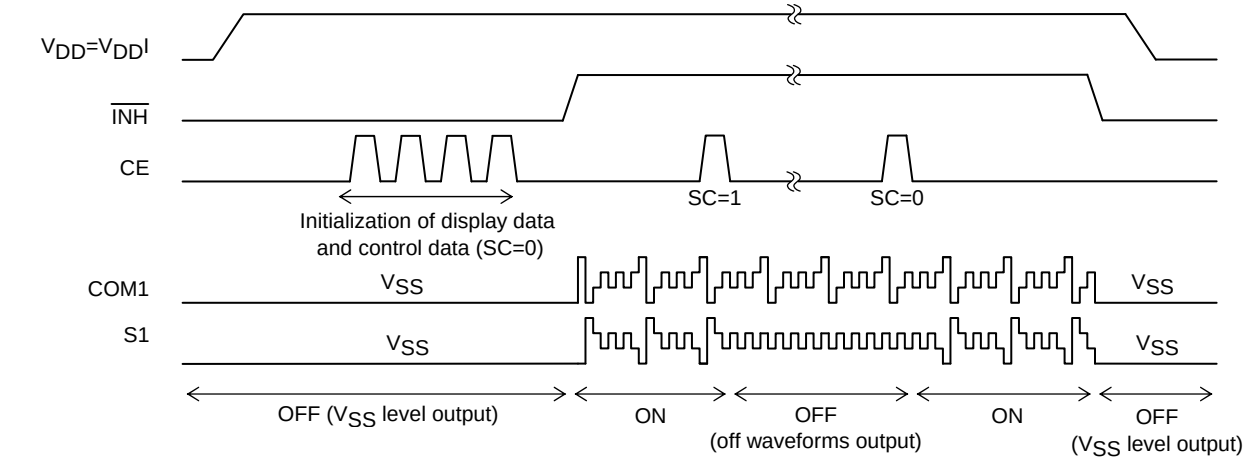
• In external clock operating mode



(Note) The wait time (t1) which power supply turn on should be 1ms or more.
The discharge time (t2) of LCD panel's electric charge should be decided the optimum value according to the characteristic of the LCD panel.
The switching time (tc) of INH should be 10μs or more.
OSCI pad should be input an external clock at INH is high level.

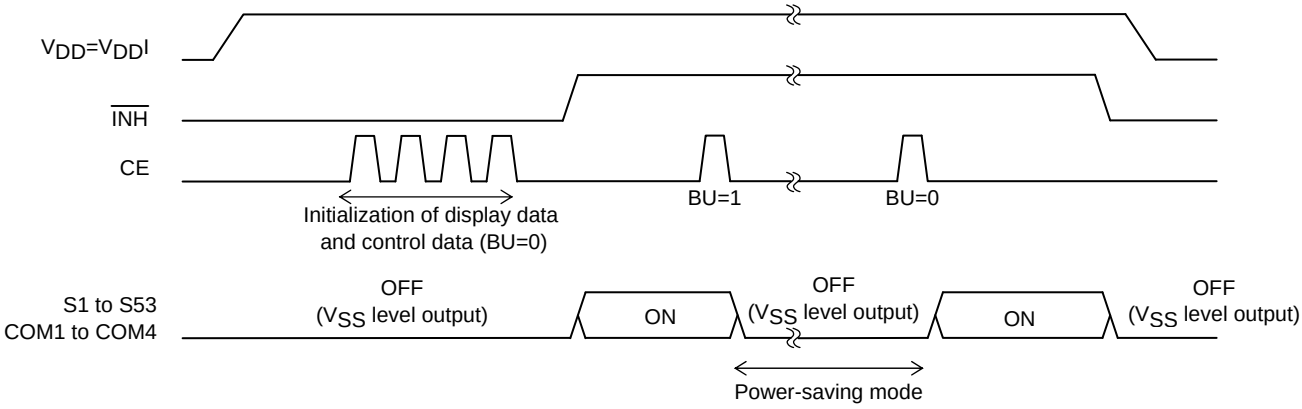
[Figure 7]

• All segments off (off waveforms output)



[Figure 8]

• Power-saving mode



[Figure 9]

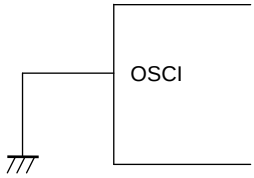
Notes on Controller Transfer of Display Data

When using the LC450029PKB in 1/4 duty, applications transfer the display data (D1 to D208) in four operations, and in 1/3 duty, they transfer the display data (D1 to D159) in three operations. In either case, applications should transfer all of the display data within 30ms to maintain the quality of displayed image.

About peripheral circuit of the input pad

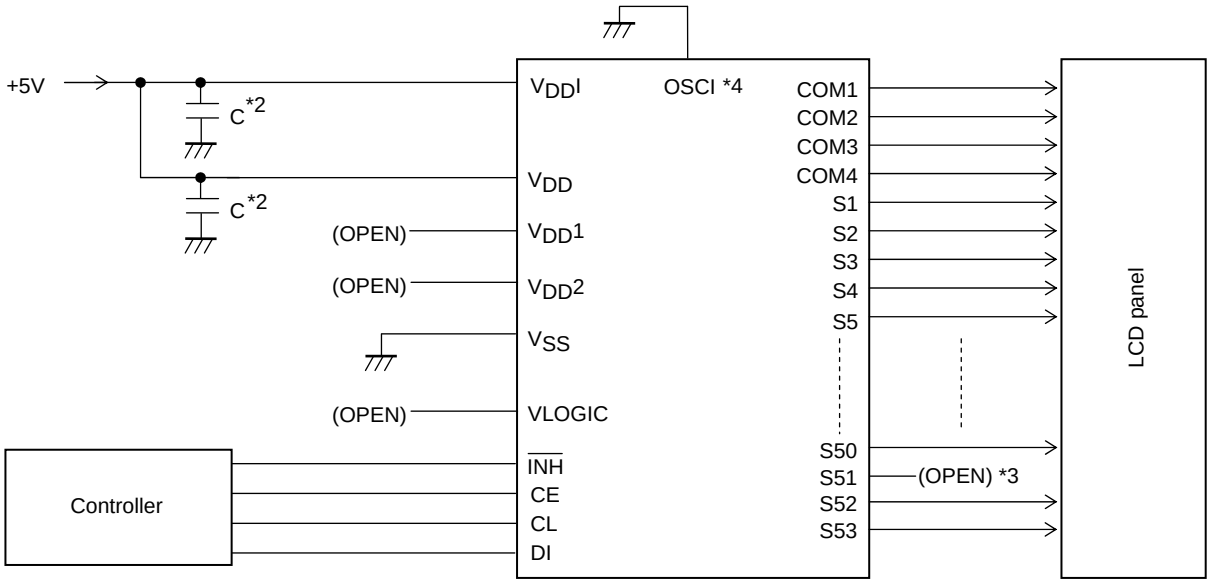
(1) Processing of unused OSCI pad

When OSCI pad is not to be used, select the internal oscillator operating mode (control data OC="0"), and OSCI pad is connected to GND.



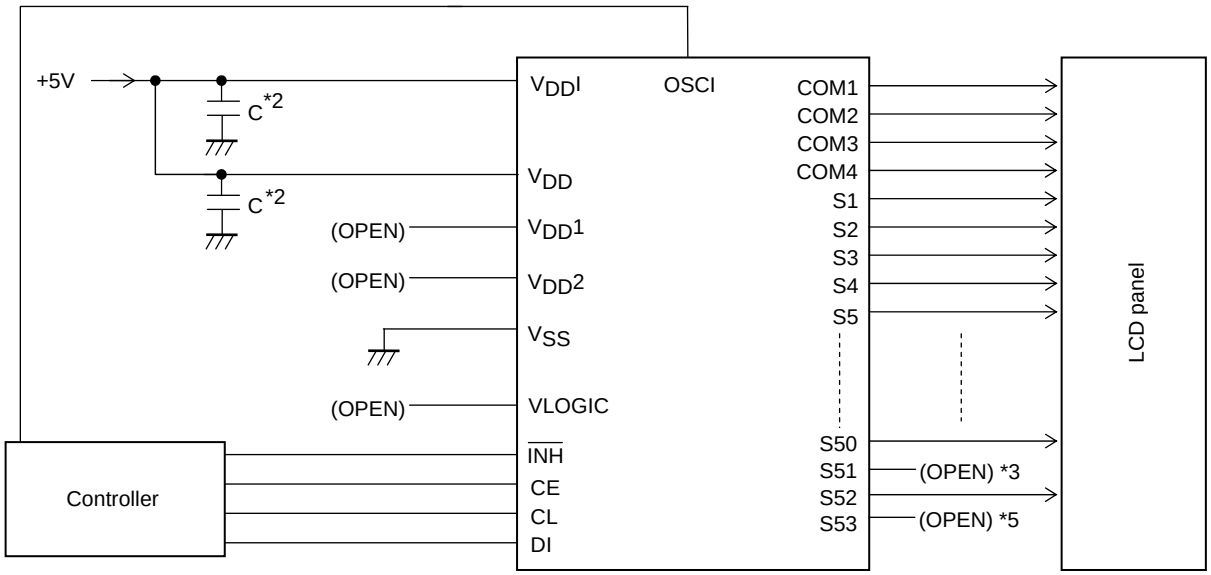
Sample Applications Circuit 1

1/4 duty, Display data (D1 to D208), Internal oscillator operating mode



Sample Applications Circuit 2

1/4 duty, Display data (D1 to D204), External clock operating mode



*2 Connect capacitors between a power supply line and GND for noise removal and power supply stabilization. Determine the value of a capacitor, after an actual circuit board estimates.

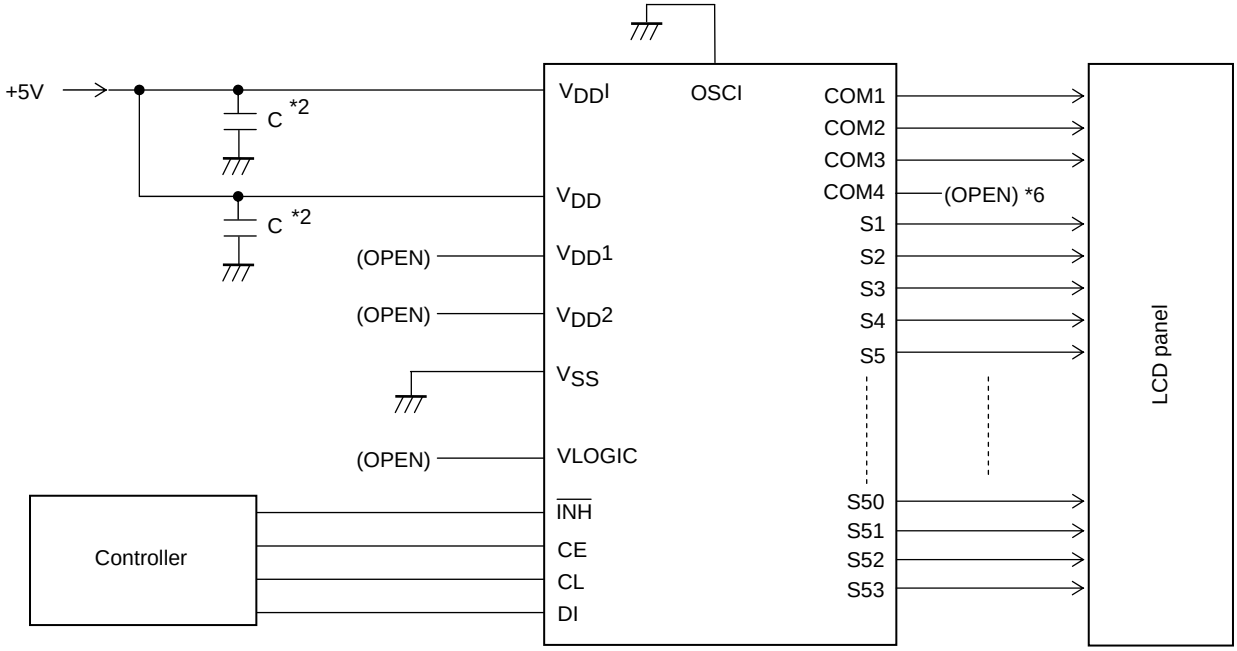
*3 In 1/4 duty, S51 pad outputs V_{SS} level.

*4 When OSCI pad is not to be used, select the internal oscillator operating mode (control data OC="0"), and OSCI pad is connected to GND.

*5 In external clock operating mode, S53 pad outputs V_{SS} level.

Sample Applications Circuit 3

1/3 duty, Display data (D1 to D159), Internal oscillator operating mode



*2 Connect capacitors between a power supply line and GND for noise removal and power supply stabilization. Determine the value of a capacitor, after an actual circuit board estimates.

*6 In 1/3 duty, COM4 pad outputs V_{SS} level.

The Notes on Use

Important things for stability operation of IC are shown as follows. The contents indicated below do not guarantee IC operation and the characteristic. Moreover, the example of an application circuit written in these specifications is for explaining internal operation and usage. Therefore, please perform the design in consideration of the specification of operation and terms and conditions in the actual LCD panel.

(1) The design of power supply
All power supply pads are connected to the power supply, and do not set open.

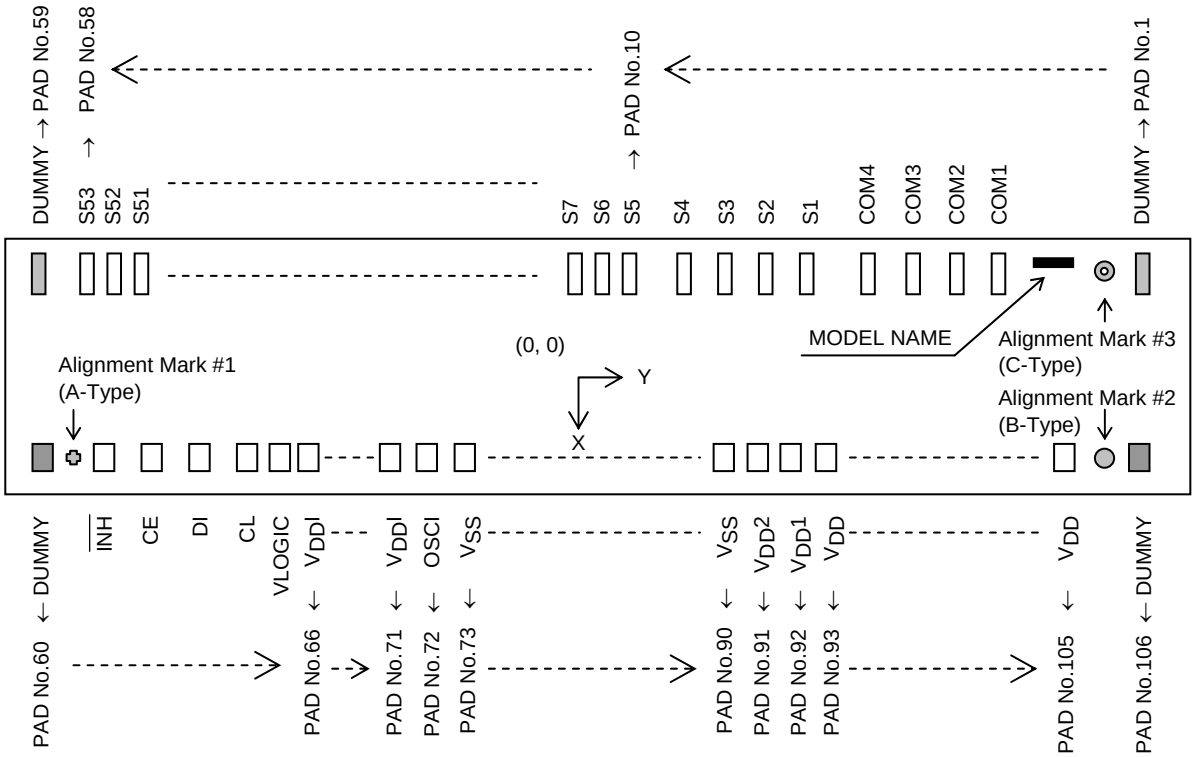
(2) ITO (Indium Tin Oxide) wiring
By designing the wire of power supply (V_{DD}, $V_{DD}I$, V_{SS}) wide and short, make the parasitic resistance of ITO wiring into the minimum.

(3) Signal wiring and connection
The DUMMY pad does not connect to anywhere, and sets open.

(4) Processing of unused input pad
For CMOS process, if an input pad is in open state, operation of IC may become unstable, or unnecessary power supply current may flow through it. Please be sure to connect the empty pad of a logic input to V_{SS}.

(5) The measure against shading
The optical irradiation to IC causes the mis-operation of IC. When IC is implemented, take the measures against shading about the surface, back and side of IC.

• PAD Locations (Bump Side View)



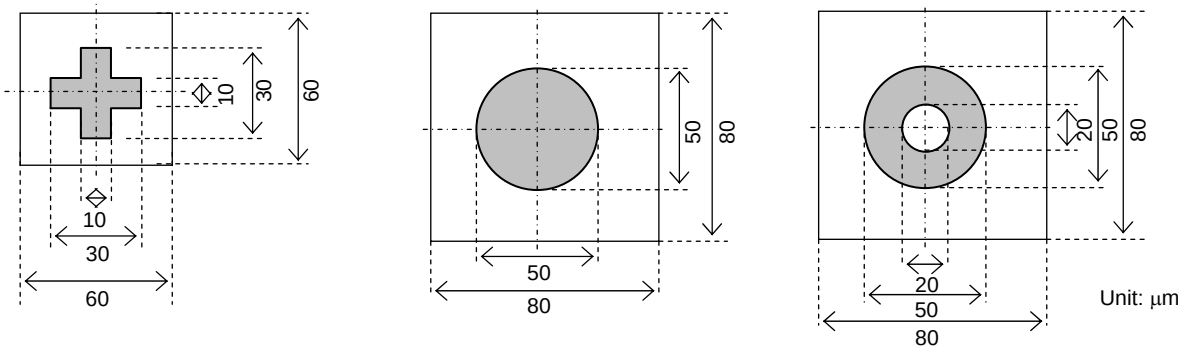
• Chip dimensions (X, Y, S are based on the dicing center.)
X=1.00mm Y=4.08mm S=4.08mm^2 Wafer thickness=400μm (typ)

• Au Bump dimensions (typ)

Item	PAD No.	Size		
		X [μm]	Y [μm]	S [μm^2]
Bump Size	1 to 59	108	27	2916
	60 to 106	68	42	2856
Min. Bump Pitch	10 to 58	50		-
	1 to 9, 59 to 106	-		-
Min. Bump Clearance	10 to 58, 66 to 71, 73 to 90, 93 to 105	23		-
	1 to 9, 59 to 65, 72, 91 to 92, 106	-		-
Bump Height	All pads	17		-

• Alignment marks

(1) A-Type (2) B-Type (3) C-Type



• Center coordinates of PADs

(All x/y coordinates represent the position of the center of each PAD)

PAD No.	PAD Name	X [μm]	Y [μm]
1	DUMMY	-380	1950
2	COM1	-380	1369
3	COM2	-380	1276
4	COM3	-380	1183
5	COM4	-380	1090
6	S1	-380	932
7	S2	-380	856
8	S3	-380	780
9	S4	-380	704
10	S5	-380	607
11	S6	-380	557
12	S7	-380	507
13	S8	-380	457
14	S9	-380	407
15	S10	-380	357
16	S11	-380	307
17	S12	-380	257
18	S13	-380	207
19	S14	-380	157
20	S15	-380	107
21	S16	-380	57
22	S17	-380	7
23	S18	-380	-43
24	S19	-380	-93
25	S20	-380	-143
26	S21	-380	-193
27	S22	-380	-243
28	S23	-380	-293
29	S24	-380	-343
30	S25	-380	-393
31	S26	-380	-443
32	S27	-380	-493
33	S28	-380	-543
34	S29	-380	-593
35	S30	-380	-643
36	S31	-380	-693
37	S32	-380	-743
38	S33	-380	-793
39	S34	-380	-843
40	S35	-380	-893
41	S36	-380	-943
42	S37	-380	-993
43	S38	-380	-1043
44	S39	-380	-1093
45	S40	-380	-1143
46	S41	-380	-1193
47	S42	-380	-1243
48	S43	-380	-1293
49	S44	-380	-1343
50	S45	-380	-1393
51	S46	-380	-1443
52	S47	-380	-1493
53	S48	-380	-1543
54	S49	-380	-1593
55	S50	-380	-1643
56	S51	-380	-1693
57	S52	-380	-1743
58	S53	-380	-1793
59	DUMMY	-380	-1950
60	DUMMY	400	-1943
61	$\overline{INH}$	400	-1665
62	CE	400	-1525
63	DI	400	-1385
64	CL	400	-1245
65	VLOGIC	400	-1161
66	$V_{DD}I$	400	-1071
67	$V_{DD}I$	400	-1006
68	$V_{DD}I$	400	-941
69	$V_{DD}I$	400	-876
70	$V_{DD}I$	400	-811
71	$V_{DD}I$	400	-746
72	OSCI	400	-650
73	V_{SS}	400	-510
74	V_{SS}	400	-445
75	V_{SS}	400	-380
76	V_{SS}	400	-315
77	V_{SS}	400	-250
78	V_{SS}	400	-185
79	V_{SS}	400	-120
80	V_{SS}	400	-55
81	V_{SS}	400	10
82	V_{SS}	400	75
83	V_{SS}	400	140
84	V_{SS}	400	205
85	V_{SS}	400	270
86	V_{SS}	400	335
87	V_{SS}	400	400
88	V_{SS}	400	465
89	V_{SS}	400	530
90	V_{SS}	400	595
91	$V_{DD}2$	400	668
92	$V_{DD}1$	400	739
93	V_{DD}	400	811
94	V_{DD}	400	876
95	V_{DD}	400	941
96	V_{DD}	400	1006
97	V_{DD}	400	1071
98	V_{DD}	400	1136
99	V_{DD}	400	1201
100	V_{DD}	400	1266
101	V_{DD}	400	1331
102	V_{DD}	400	1396
103	V_{DD}	400	1461
104	V_{DD}	400	1526
105	V_{DD}	400	1591
106	DUMMY	400	1943

• Center coordinates of alignment marks

(All x/y coordinates represent the position of the center of each alignment mark)

Alignment mark	TYPE	X [μm]	Y [μm]
1	A	400	-1800
2	B	400	1790
3	C	-380	1800

ORDERING INFORMATION

Device	Package	Shipping (Qty / Packing)
LC450029PKB-XT	Wafer (Pb-Free)	1 / Waffle Pack

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